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Product Change Notification - JAON-20QUIV826 [\(Printer Friendly\)](#)

Date: 30 Jul 2015

Notification subject: CCB 1707 Initial Notice: Qualification of CuPdAu bond wire and G700LS molding compound in selected products of the 200K wafer technology available in 28L SSOP package at ANAP assembly site.

Notification text:

PCN Status:
Initial notification

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of palladium coated copper with gold flash (CuPdAu) bond wire and G700LS molding compound in selected products of the 200K wafer technology available in 28L SSOP package at ANAP assembly site.

Pre Change:
Gold wire (Au) and G600 molding compound.

Post Change:
Palladium coated copper wire with gold flash (CuPdAu) and G700LS molding compound.

Impacts to Data Sheet:
None

Reason for Change:
To improve manufacturability and qualify palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:
In Progress

Estimated First Ship Date:
November 15, 2015 (date code: 1546)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Markings to Distinguish Revised from Unrevised Devices:
Traceability code

Revision History:
July 30, 2015: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_JAON-20QUIV826_Qual_Plan.pdf](#)
[PCN_JAON-20QUIV826_Affected_CPN.pdf](#)
[PCN_JAON-20QUIV826_Affected_CPN.xls](#)

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